

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SAI-HOOI YEONG	01/31/2018
SHENG-CHEN WANG	01/31/2018
BO-YU LAI	01/31/2018
ZIWEI FANG	02/13/2018
FENG-CHENG YANG	01/31/2018
YEN-MING CHEN	01/31/2018
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	8, LI-HSIN RD 6
Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17815857
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2109787404
Email:	lori.lapidario@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP - IP SECTION
Address Line 1:	2323 VICTORY AVENUE, SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	2016-0800/24061.3469US04
NAME OF SUBMITTER:	LORI LAPIDARIO
SIGNATURE:	/Lori Lapidario/
DATE SIGNED:	07/28/2022

Total Attachments: 3

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ASSIGNMENT

WHEREAS, we,

- (1) Sai-Hooi Yeong of Hsinchu County, Taiwan, (R.O.C.)
- (2) Sheng-Chen Wang of Hsinchu City, Taiwan, (R.O.C.)
- (3) Bo-Yu Lai of Taipei City, Taiwan, (R.O.C.)
- (4) Ziwei Fang of Hsinchu, Taiwan, (R.O.C.)
- (5) Feng-Cheng Yang of Hsinchu County, Taiwan, (R.O.C.)
- (6) Yen-Ming Chen of Hsin-Chu County, Taiwan, (R.O.C.)

have invented certain improvements in

**CONFORMAL TRANSFER DOPING METHOD FOR
FIN-LIKE FIELD EFFECT TRANSISTOR**

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on July 19, 2017 and assigned application number 15/653,720; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on

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Customer No.: 000042717

applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

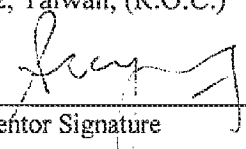
AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: SAI-HOOI YEONG

Residence Address: 6F.-2, No.128, Sec. 1, Liujia 1st Rd.,
Zhubei City, Hsinchu County 302, Taiwan, (R.O.C.)

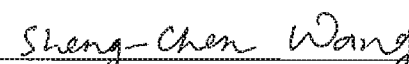
Dated: 2018/1/31


Inventor Signature

Inventor Name: SHENG-CHEN WANG

Residence Address: 4F, No.12, Ln. 185, Xinzhuang St., East District
Hsinchu City 300, Taiwan (R.O.C.)

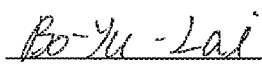
Dated: 2018/1/31


Inventor Signature

Inventor Name: BO-YU LAI

Residence Address: 5F., No.1, Wanqing St.,
Wenshan District, Taipei City 116, Taiwan, (R.O.C.)

Dated: 2018/1/31


Inventor Signature


Docket No.: P20160800US00/24061.3469US01

Customer No.: 000042717

Inventor Name: ZIWEI FANG

Residence Address: 9 Songcui Road 17th Lane, Baoshan Township
Hsinchu, Taiwan, (R.O.C.)

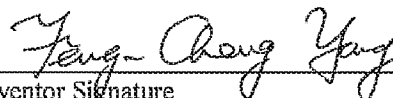
Dated: 2/13/2018


Inventor Signature

Inventor Name: FENG-CHENG YANG

Residence Address: No. 7, Aly. 8, Ln. 315, Xuefu E. Rd.
Zhudong Township, Hsinchu County 310, Taiwan, (R.O.C.)

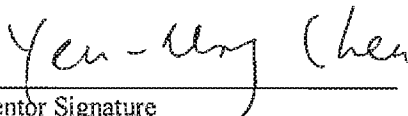
Dated: 2018/1/31


Inventor Signature

Inventor Name: YEN-MING CHEN

Residence Address: 6F, No. 33, Sheng-Li 5th Rd.,
Chu-Pei City, Hsin-Chu County, Taiwan, (R.O.C.)

Dated: 2018/1/31


Inventor Signature